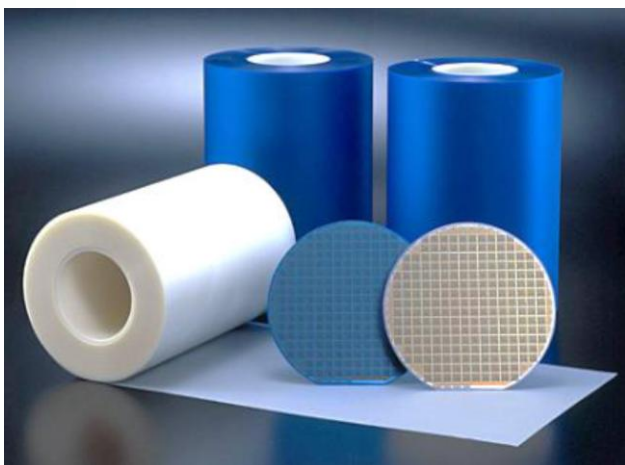


UV & Non-UV Wafer Dicing Tape



- ✓ Good working process for Semiconductor, Glass, PCB etc.
- ✓ A various Line-up for usage such as PO, PVC, PET Base UV, Non-UV Dicing Film

Item	Unit	Non-UV Dicing				UV Dicing				
		EO-DA110	EO-DA085	ET-RE090	EO-DA090	EO-BG170	EP-DB90	EP-DW090	ET-DC125	
Base Film	Type	-	PO	PO	PET	PO	PO	PVC (Blue)	PVD (White)	PET
	Thickness	μm	80	80	50	80	150	80	80	100
Adhesive Thickness		μm	30	5	40	10	20	10	10	25
Young's modulus (MD)		kgf/cm	550	550	-	550	900	1200	1200	-
Tensile Strength (MD)		gf	1200	1200	-	1200	2100	1900	1900	-
Elongation (MD)		%	300	300	-	300	400	200	200	-
Peeling Force (BF UV)		gf/inch	40-60	20-30	1500-1600	50-150	1500-2000	200-300	200-300	1500-2000
Peeling Force (AF UV)		gf/inch	-	-	-	20	30	30	30	10

UV & Non-UV Dicing Tape (B/G Dicing Process)

